

ABSTRACT:

The invention relates to an arrangement of a chemical-mechanical polishing tool for chemical-mechanical polishing a surface on a wafer, comprising a polishing pad (4), a drive unit (9), pressing means (6), a wafer holder (5), first dispensing means (7) and second dispensing means (8); the wafer holder for holding a wafer (W) being arranged at a holder location (L0); the pressing means (6) being arranged to press the wafer holder (5) to the polishing pad (4); the first dispensing means (7) for dispensing a first fluid on the polishing pad (4) being arranged at a first dispensing means location (L1); the second dispensing means (8) for dispensing a second fluid on the polishing pad (4) being arranged at a second dispensing means location (L2); the polishing pad (4) comprising a polishing surface for polishing the wafer (W), and the polishing pad (4) further being connected to the drive unit (9) for moving the polishing surface in a first direction (ω_1) relative to the holder location (L0);

wherein the first dispensing means location (L1) of the first dispensing means (7) is arranged in a downstream direction with respect to the holder location (L0) at a first downstream distance (d1), with the downstream direction being taken in relation to the first direction (ω_1); and the second dispensing means location (L2) of the second dispensing means (8) is arranged in an upstream direction with respect to the holder location (L0) at a first upstream distance (d3), with the upstream direction being taken in relation to the first direction (ω_1).

The invention further relates to a method of chemical-mechanical polishing using such an arrangement.

Fig. 2